

EAISI - [0932555.wpd] [X]

Drafts Pending Active

- L1: (554567) (base flexible bend tape shaped tab interconnect carrier film) with substrate
- L2: (122121) reel
- L3: (128331) 2 reeling reeled
- L4: (54666) (interconnect wiring tracing) with pattern
- L5: (74510) (interconnect lead leadframe wiring tracing) with pattern
- L6: (254) 1 and 3 and 5
- L7: (42162) (base flexible bend tape shaped tab interconnect carrier film substrate) and 4
- L8: (35324) (base flexible bend tape shaped tab interconnect carrier film substrate) same 4
- L9: (44716) (base flexible bend tape shaped tab interconnect carrier film substrate) same 5
- L10: (112) 9 same 3
- L11: (76) 10 not 6

Failed

- (0) base flexible bend tape shaped tab interconnect carrier film substrate

Saved

- (96375) (bendable flexible moveable) with (frame container supporter)
- (1808) (chip die dice ic (integrated adj circuit)) same ((bendable flexible moveable) with (frame container supporter))
- (51221) (bendable flexible moveable) with (frame)
- (1235) ((chip die dice ic (integrated adj circuit)) same ((bendable flexible moveable) with (frame container supporter)))
- (432) (((chip die dice ic (integrated adj circuit)) same ((bendable flexible moveable) with (frame container supporter)))
- (432) (((chip die dice ic (integrated adj circuit)) same ((bendable flexible moveable) with (frame container supporter)))
- (96375) ((bendable flexible moveable) with (frame container supporter))
- (1808) ((bendable flexible moveable) with (frame container supporter)) and ((chip die dice ic (integrated adj circuit)) same ((bendable flexible moveable) with (frame container supporter)))
- (1235) ((bendable flexible moveable) with (frame container supporter)) and ((chip die dice ic (integrated adj circuit)) same ((bendable flexible moveable) with (frame container supporter)))
- (432) (((bendable flexible moveable) with (frame container supporter))) and ((chip die dice ic (integrated adj circuit)) same ((bendable flexible moveable) with (frame container supporter)))

Favorites

Filtered (0)

U	I	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Retrieval C	Inventor	S	C	P	E	U
1.	<input type="checkbox"/>	<input type="checkbox"/>	US 20020044383	20020418	30	Magnetic tape cassette	360/132		Ashikawa, Teruo et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
2.	<input type="checkbox"/>	<input type="checkbox"/>	US 20010051319	20011220	7	Progressively-formed clinch nut	411/437		Swanstrom, Kenneth A. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
3.	<input type="checkbox"/>	<input type="checkbox"/>	US 6216342 B1	20010417	41	Method for fabricating a matrix switchboard and	29/852	29/846;	Hosogai, Masao et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
4.	<input type="checkbox"/>	<input type="checkbox"/>	US 5886309 A	19990323	41	Matrix switch board, connection pin, and method	200/1R	200/175;	Hosogai, Masao et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
5.	<input type="checkbox"/>	<input type="checkbox"/>	US R235950 B	19981110	24	Recording medium cassette and a recording/reproducing	242/344	439/48	Sawada, Takashi et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
6.	<input type="checkbox"/>	<input type="checkbox"/>	US 5808355 A	19980915	9	Lead frame of a semiconductor device and a	257/666	257/669;	Kim, Yong-yeon et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
7.	<input type="checkbox"/>	<input type="checkbox"/>	US 5632528 A	19970527	11	Lead frame structure for IC devices with strengthened	257/666	257/672;	Abbott, Donald C. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
8.	<input type="checkbox"/>	<input type="checkbox"/>	US 5610437 A	19970311	9	Lead frame for integrated circuits	257/670	257/676;	Frechette, Raymond A.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
9.	<input type="checkbox"/>	<input type="checkbox"/>	US 5592734 A	19970114	33	Method and apparatus for framing a film mounted	257/670	257/666;	Houghton, Jon C. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
10.	<input type="checkbox"/>	<input type="checkbox"/>	US 5502395 A	19960326	6	Semiconductor device burn-in apparatus	29/827	29/827	Wada, Shinobu	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
11.	<input type="checkbox"/>	<input type="checkbox"/>	US 5448877 A	19950912	11	Method for packing lead frames for shipment thereof	324/760	324/419;	Chu, Hsiang	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
							324/537;							
							33/472;							
							33/475							

Details  HTML

Ready